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AME	MOMENT TO NO.	TRANSMI	TTAL LE	TTER	Docket No. 0941-0924P
Applicatio	n No.	Filing	Date	Examiner	0941-0924P
10/791,816-Conf. #003667		March 4	1	S. Hu	2811
plicant(s): Min-	hung Lee et al				
	NED SILICON DD THEREOF	CARBON ALL	OY MOSFET	STRUCTURE AND	FABRICATION
Amendment mmissioner for l D. Box 1450 exandria, VA 223 ransmitted here	313-1450	ndment in the	above-identif	ied application.	
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	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
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Charge 2	ny additional fili	ng or applicatio	n processing t	ees required under 37	CFR 1.16 and 1.17.
Joe McKinney M Attorney Reg. N		1		Dated:	July 28, 2005
BIRCH, STEWA	ART, KOLASCI	∮ & BIRCH, LL	P		
Suite 100 East P.O. Box 747	1	1747			
Falls Church, Vi	igilia 22040-0)			
Falls Church, Vi (703) 205-8026	rgilla 22040-0)			



Docket No.: 0941-0924P

(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Min-hung Lee et al.

Application No.: 10/791,816

Confirmation No.: 003667

Filed: March 4, 2004

Art Unit: 2811

For: STRAINED SILICON CARBON ALLOY

MOSFET STRUCTURE AND FABRICATION

METHOD THEREOF

Examiner: S. Hu

AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

INTRODUCTORY COMMENTS

In reply to the Office Action dated April 28, 2005, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

This reply includes:

Amendments to the Specification;

Amendments to the Claims; and

Remarks.